Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	461	438/244.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 09:56
S1	8	("5091047"|"5340435"|"5966628"|"6150969").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 06:59
S2	10	((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:53
S3	4	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 07:02
S4	10	((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 08:48
S5	3	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 08:45
S6	1627	((etch or etching) with edge) and (barrier adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 08:49
S7	412	(((etch or etching) with edge) and (barrier adj layer)) and (barrier with edge)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 08:50
S8	113	(((etch or etching) with edge) and (barrier adj layer)) and (barrier with edge with etch)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:01
S9	20	((((etch or etching) with edge) and (barrier adj layer)) and (barrier with edge with etch)) and acid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:02

S10	10	((((etch or etching) with edge) and (barrier adj layer)) and (barrier with edge with etch)) and (acid with etch)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:02
S11	3	(US-6615854-$ or US-6451696-$ or US-6784051-$).did.	USPAT	OR	OFF	2004/11/01 09:37
S12	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (second with etch)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:39
S13	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (second with etchant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:38
S14	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (first with etchant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:38
S15	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (first with etch)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:39
S16	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (air-tight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:53
S17	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (air adj tight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:53
S18	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (sealed with chamber)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:55
S19	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (sealed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:48
S20	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (chamber)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:49

S21	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (etch with air)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:49
S22	1	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (air)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:50
S23	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (ambient)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:54
S24	0	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (gaseous)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:54
S25	1	((US-6615854-$ or US-6451696-$ or US-6784051-$).did.) and (nitric with oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:54
S26	10	((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:53
S27	0	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and (air-tight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:53
S28	0	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and (air adj tight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:54
S29	1	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and (ambient)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:54
S30	0	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and (gaseous)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:54

S31	1	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and (nitric with oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:55
S32	0	(((etch or etching) with edge) and (diluted with nitric with hydrofluoric with acid)) and (sealed with chamber)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 09:55
S33	4	("6211086"|"6379782").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 15:18
S34	4	("6211429"|"6077710").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 15:18
S35	8	S33 OR S34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/17 15:19
S36	4519	edge with substrate with (etch or etching or etchant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:08
S37	2022	S36 and ((etch or etching or etchant) with (first and second))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:10
S38	2	S37 and ((remove or removing) with (barrier adj layer) with (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:16
S39	42	S36 and (first adj etchant) and (second adj etchant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:15
S40	1	S39 and ((remove or removing) with (barrier adj layer) with (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:16

S41	4	S36 and ((remove or removing) with (barrier adj layer) with (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:36
S42	4	("6211086"|"6379782").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:37
S43	0	S42 and (first adj etchant) and (second adj etchant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:38
S44	0	S42 and (second adj etchant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:38
S45	0	S42 and (barrier adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:39
S46	0	S42 and (metal adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:39
S47	1	S42 and (nitric adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:40
S48	1	S42 and (hydrofluoric adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/14 11:40